

## PCB Stack-up and Technical Requirements

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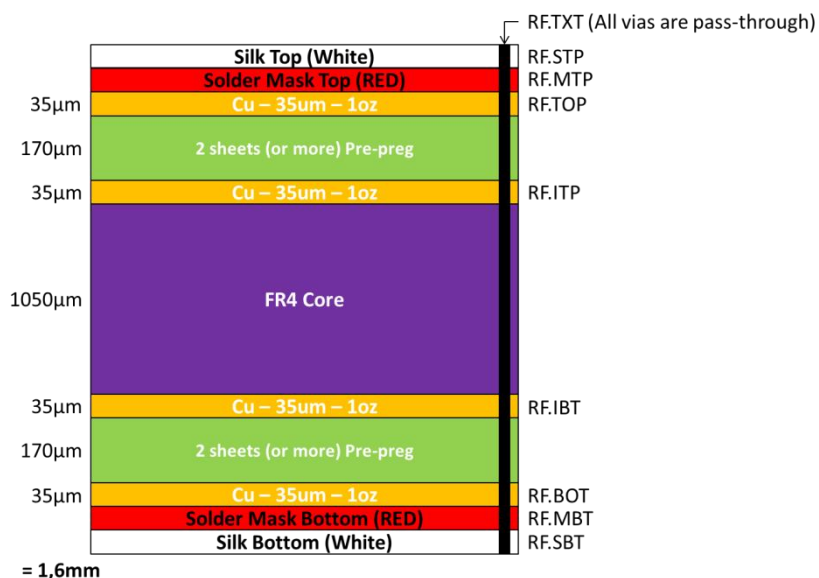
Our minimum specifications are as follow:

Number of layers:	4 layers
Minimum line width ( $\leq$ ):	4mil / 0,106mm
Minimum line spacing/gap ( $\leq$ ):	4mil / 0,106mm
Minimum Annular Ring ( $\leq$ ):	4mil / 0,106mm
Minimum mechanical hole size ( $\leq$ ):	8mil / 0,2mm
Surface finish:	ENIG
Electrical Test:	100% Electrical Test (E-Test)
Substrate type:	FR-4 High Tg ( $\geq 170^{\circ}\text{C}$ )

### Stencil:

Please quote 2 stencils (Stencil 1: RF\_STENCIL.TOP and Stencil 2: RF\_STENCIL.BOT). Both of them should be **framed** and have a **frame size of 29"**. The global fiducials for the stencil are indicated on the top-left, bottom-left and bottom-right corners of the stencil files. The fiducials shall not be considered as openings for solder paste. The stencil shall be made in **stainless steel** and **laser cut**. The fiducials shall be produced in order to ensure good alignment and many production cycles. **Thickness is 5 mils**.

### PCB Stack-up and files:



### Quantities:

- 1 x 29" framed stencil (RF\_STENCIL.TOP)
- 1 x 29" framed stencil (RF\_STENCIL.BOT)
- 1998 x PCBs (333 panels)